



Product Update Memo

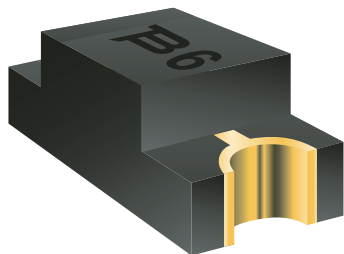
CHIP DIODES

September, 2006

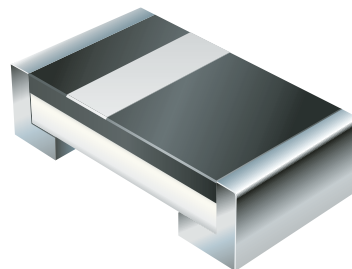
Bourns Manufacturers Representatives
Corporate Distributor Product Managers
Americas Sales Team
Asia Sales Team
Europe Sales Team

Product Change Notice Bourns® CD1206-S01575 Chip Diode Package Change

Over the past twelve months, Bourns has incurred large material cost increases for the packaging of chip diode products, especially the substrate and copper and gold materials. In addition, lead times for raw materials have increased. To ensure continued product delivery, competitive pricing and support to our customers on the CD1206-S01575 device, Bourns will initiate an immediate product change from the BT substrate package to the ceramic package assembly on the switching diode device.



Current Package



NEW Package

Electrical specifications will remain unchanged. Bourns will offer the new replacement CD1206-S01575 device at the same price as the previous version. See the Bourns Price Book for more details.

Effective immediately, no further orders for the old package format will be accepted. On all new orders, the new ceramic type package will be used for the CD1206-S01575 model. The product [data sheet](#) with detailed specifications can be viewed on the Bourns website at www.bourns.com. Samples are available upon request.
